



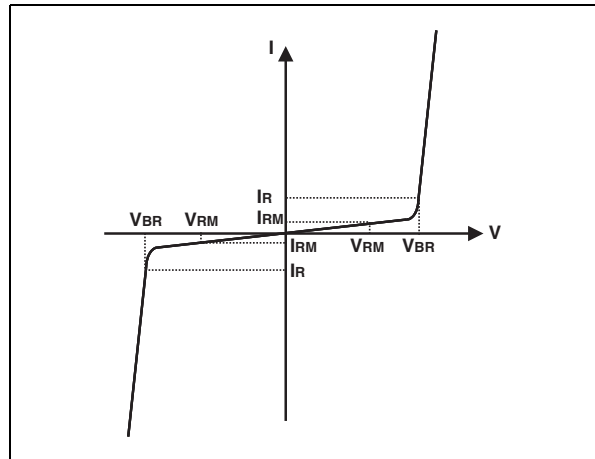
## EMIF04-VID01C1

**Table 2: Absolute Ratings** (limiting values)

Symbol	Parameter and test conditions	Value	Unit
$T_j$	Maximum junction temperature	125	°C
$T_{op}$	Operating temperature range	- 40 to + 85	°C
$T_{stg}$	Storage temperature range	- 55 to + 150	°C

**Table 3: Electrical Characteristics** ( $T_{amb} = 25^\circ\text{C}$ )

Symbol	Parameter
$V_{BR}$	Breakdown voltage
$I_{RM}$	Leakage current @ $V_{RM}$
$V_{RM}$	Stand-off voltage
$R$	Series resistance between Input & Output
$C_{line}$	Input capacitance per line



Symbol	Test conditions	Min.	Typ.	Max.	Unit
$V_{BR}$	$I_R = 1\text{mA}$	6	8	10	V
$I_{RM}$	$V_{RM} = 3\text{V per line}$			500	nA
$R$	$I = 10\text{mA}$	80	100	120	$\Omega$
$C_{line}$	$V_R = 3\text{V DC}$ $1\text{MHz}$ $V_{OSC} = 30\text{mV}$		16	19	pF

Figure 3: S21 (dB) attenuation measurement

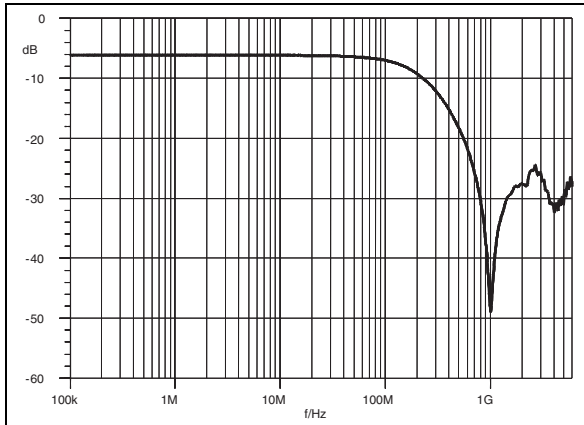


Figure 4: Analog crosstalk measurement

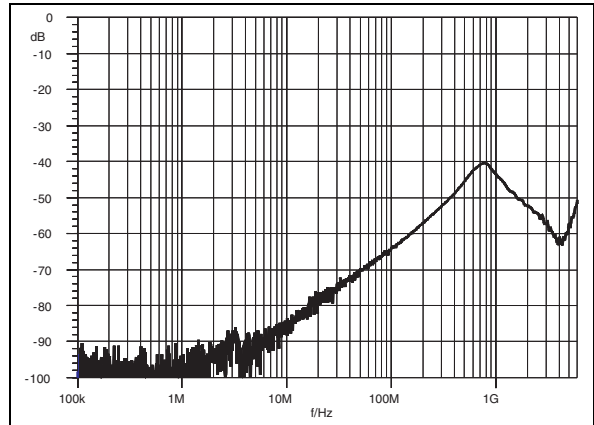


Figure 5: ESD response to IEC61000-4-2 (+15kV air discharge) on one input V(in) and on one output (Vout)

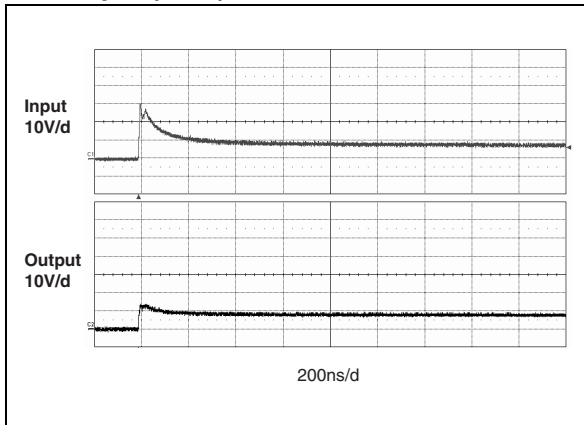


Figure 6: ESD response to IEC61000-4-2 (-15kV air discharge) on one input V(in) and on one output (Vout)

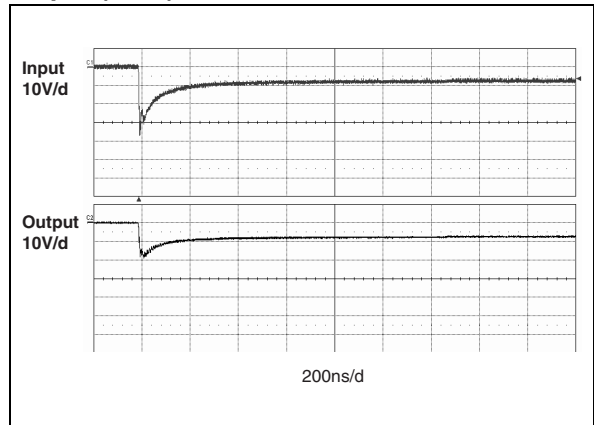


Figure 7: Junction capacitance versus reverse voltage applied (typical values)

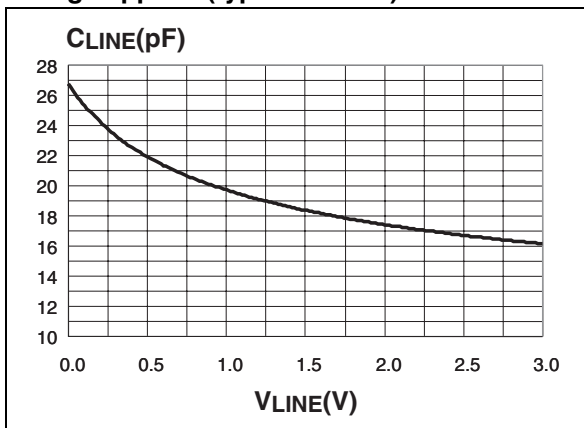


Figure 8: Ordering Information Scheme

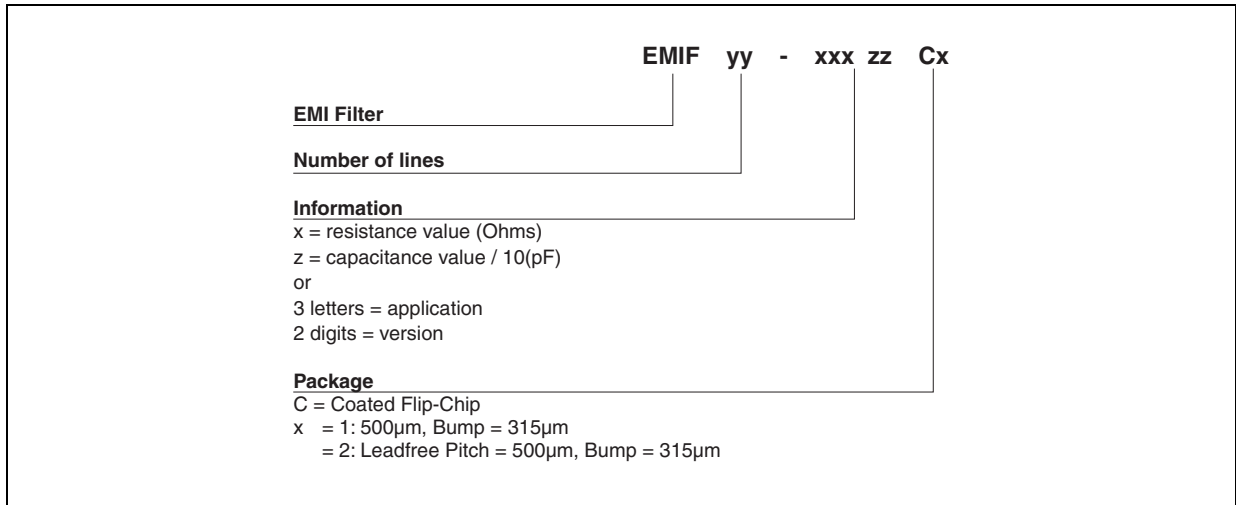


Figure 9: FLIP-CHIP Package Mechanical Data

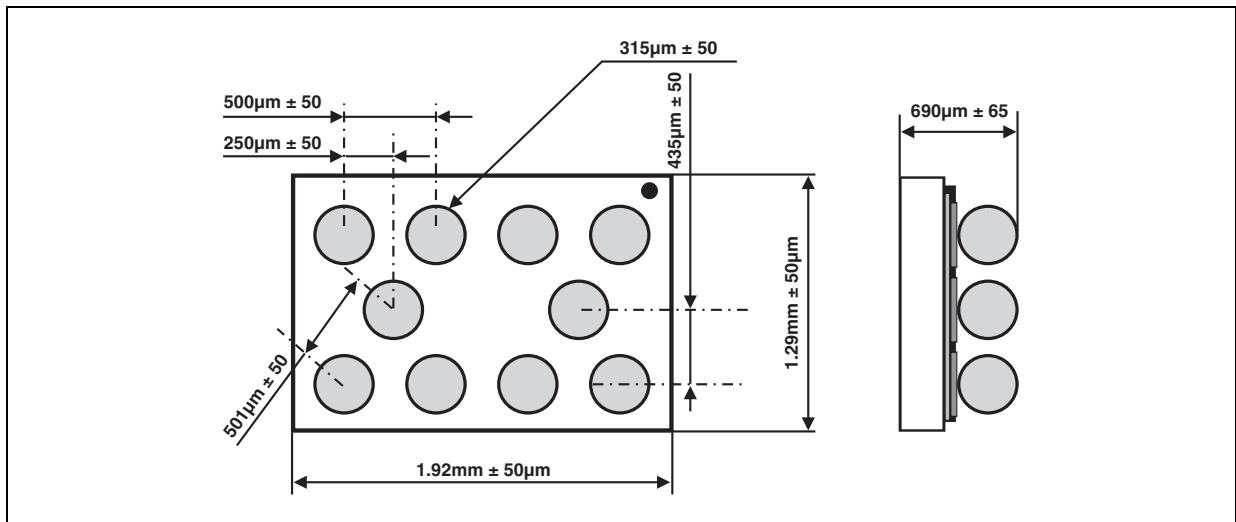


Figure 10: Foot Print Recommendations

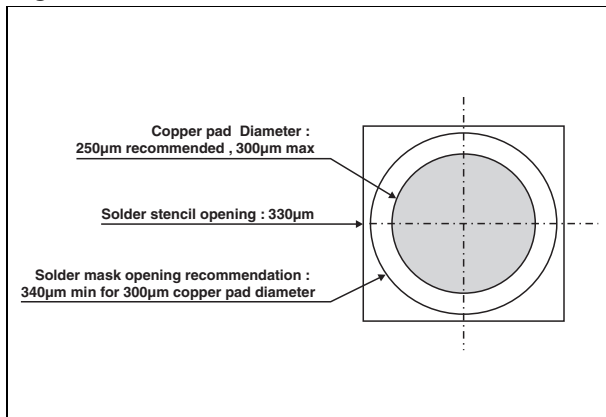


Figure 11: Marking

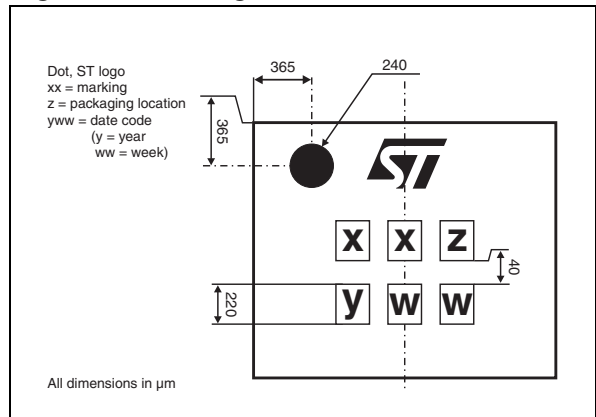


Figure 12: FLIP-CHIP Tape and Reel Specification

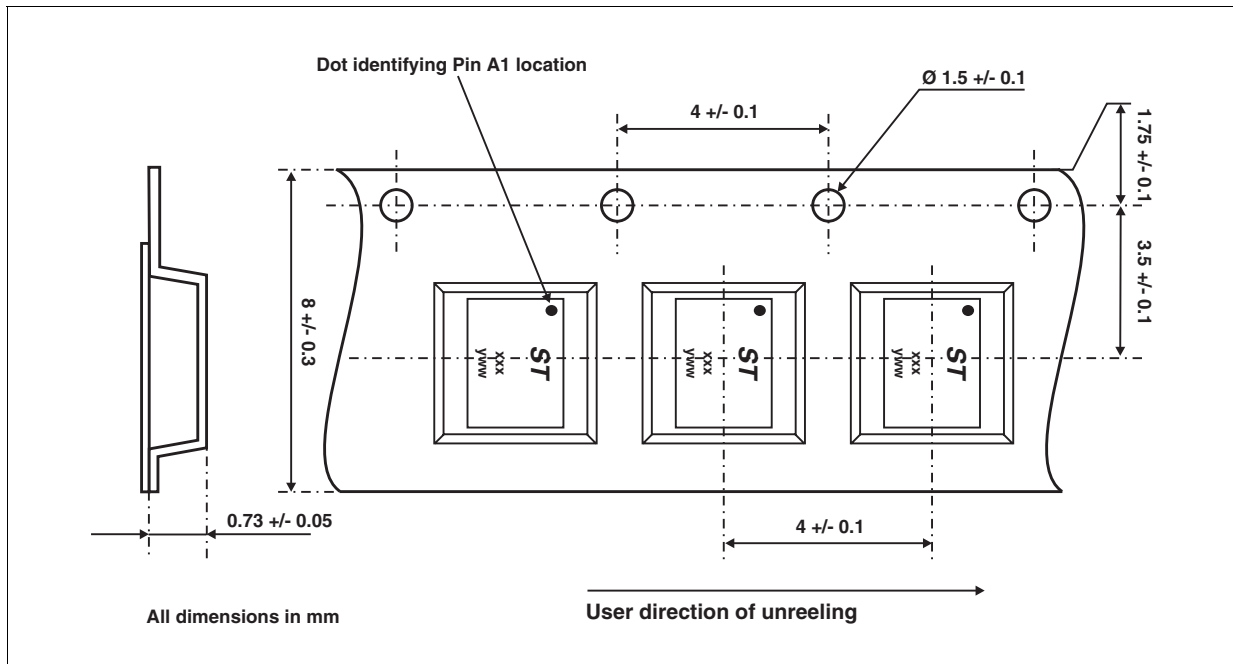


Table 4: Ordering Information

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
EMIF04-VID01C1	GU	Flip-Chip	3.9 mg	5000	Tape & reel 7"

**Note:** More packing informations are available in the application note  
 AN1235: "Flip-Chip: Package description and recommendations for use"  
 AN1751: "EMI Filters: Recommendations and measurements"

Table 5: Revision History

Date	Revision	Description of Changes
15-Feb-2005	1	First issue.

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics.  
All other names are the property of their respective owners

© 2005 STMicroelectronics - All rights reserved

**STMicroelectronics group of companies**

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -  
Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America  
[www.st.com](http://www.st.com)